Zilog - ZGP323HAH4804C00TR Datasheet

Details	
Product Status	Obsolete
Core Processor	Z8
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	HLVD, POR, WDT
Number of I/O	32
Program Memory Size	4KB (4K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	237 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-BSSOP (0.295", 7.50mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/zgp323hah4804c00tr

Capacitance

Table 8 lists the capacitances.

Table 8. Capacitance

Parameter	Maximum
Input capacitance	12pF
Output capacitance	12pF
I/O capacitance	12pF
Note: T_A = 25° C, V_{CC} = GND = 0 V, f = 1.0 MHz, unmeasured pins returned to GND	

DC Characteristics

Table 9. GP323HS DC Characteristics

			T_A=0°C to +70°C					
Symbol	**Parameter**	**V_{CC}**	**Min**	**Typ(7)**	**Max**	**Units**	**Conditions**	**Notes**
V_{CC}	Supply Voltage		2.0		5.5	V	See Note 5	5
V_{CH}	Clock Input High Voltage	2.0-5.5	0.8 V_{CC}		V_{CC}+0.3	V	Driven by External Clock Generator	
V_{CL}	Clock Input Low Voltage	2.0-5.5	V_{SS}–0.3		0.4	V	Driven by External Clock Generator	
V_{IH}	Input High Voltage	2.0-5.5	0.7 V_{CC}		V_{CC}+0.3	V		
V_{IL}	Input Low Voltage	2.0-5.5	V_{SS}–0.3		0.2 V_{CC}	V		
V_{OH1}	Output High Voltage	2.0-5.5	V_{CC}–0.4			V	I_{OH} = –0.5mA	
V_{OH2}	Output High Voltage (P36, P37, P00, P01)	2.0-5.5	V_{CC}–0.8			V	I_{OH} = –7mA	
V_{OL1}	Output Low Voltage	2.0-5.5			0.4	V	I_{OL} = 4.0mA	
V_{OL2}	Output Low Voltage (P00, P01, P36, P37)	2.0-5.5			0.8	V	I_{OL} = 10mA	
V_{OFFSET}	Comparator Input Offset Voltage	2.0-5.5			25	mV		
V_{REF}	Comparator Reference Voltage	2.0-5.5	0		V_{CC} 1.75	V		
I_{IL}	Input Leakage	2.0-5.5	–1		1	µA	V_{IN} = 0V, V_{CC} Pull-ups disabled	
R_{PU}	Pull-up Resistance	2.0V	225		675	KΩ	V_{IN} = 0V; Pullups selected by mask option	
		3.6V	75		275	KΩ		
		5.0V	40		160	KΩ		

Table 9. GP323HS DC Characteristics (Continued)

			T_A=0°C to +70°C					
Symbol	**Parameter**	**V_{CC}**	**Min**	**Typ(7)**	**Max**	**Units**	**Conditions**	**Notes**
I_{OL}	Output Leakage	2.0-5.5	–1		1	µA	V_{IN} = 0V, V_{CC}	
I_{CC}	Supply Current	2.0V		1	3	mA	at 8.0 MHz	1, 2
		3.6V		5	10	mA	at 8.0 MHz	1, 2
		5.5V		10	15	mA	at 8.0 MHz	1, 2
I_{CC1}	Standby Current (HALT Mode)	2.0V		0.5	1.6	mA	V_{IN} = 0V, Clock at 8.0MHz	1, 2, 6
		3.6V		0.8	2.0	mA	V_{IN} = 0V, Clock at 8.0MHz	1, 2, 6
		5.5V		1.3	3.2	mA	V_{IN} = 0V, Clock at 8.0MHz	1, 2, 6
I_{CC2}	Standby Current (Stop Mode)	2.0V		1.6	8	µA	V_{IN} = 0 V, V_{CC} WDT not Running	3
		3.6V		1.8	10	µA	V_{IN} = 0 V, V_{CC} WDT not Running	3
		5.5V		1.9	12	µA	V_{IN} = 0 V, V_{CC} WDT not Running	3
		2.0V		5	20	µA	V_{IN} = 0 V, V_{CC} WDT is Running	3
		3.6V		8	30	µA	V_{IN} = 0 V, V_{CC} WDT is Running	3
		5.5V		15	45	µA	V_{IN} = 0 V, V_{CC} WDT is Running	3
I_{LV}	Standby Current (Low Voltage)			1.2	6	µA	Measured at 1.3V	4
V_{BO}	V_{CC} Low Voltage Protection			1.9	2.0	V	8MHz maximum Ext. CLK Freq.	
V_{LVD}	V_{CC} Low Voltage Detection			2.4		V		
V_{HVD}	Vcc High Voltage Detection			2.7		V		

Notes:

1. All outputs unloaded, inputs at rail.
2. CL1 = CL2 = 100 pF.
3. Oscillator stopped.
4. Oscillator stops when V_{CC} falls below V_{BO} limit.
5. It is strongly recommended to add a filter capacitor (minimum 0.1 µF), physically close to VCC and V_{SS} pins if operating voltage fluctuations are anticipated, such as those resulting from driving an Infrared LED.
6. Comparator and Timers are on. Interrupt disabled.
7. Typical values shown are at 25 degrees C.

Table 10. GP323HE DC Characteristics

			T_A= -40°C to +105°C					
Symbol	**Parameter**	**V_{CC}**	**Min**	**Typ(7)**	**Max**	**Units**	**Conditions**	**Notes**
V_{CC}	Supply Voltage		2.0		5.5	V	See Note 5	5
V_{CH}	Clock Input High Voltage	2.0-5.5	0.8 V_{CC}		V_{CC}+0.3	V	Driven by External Clock Generator	
V_{CL}	Clock Input Low Voltage	2.0-5.5	V_{SS}–0.3		0.4	V	Driven by External Clock Generator	
V_{IH}	Input High Voltage	2.0-5.5	0.7 V_{CC}		V_{CC}+0.3	V		
V_{IL}	Input Low Voltage	2.0-5.5	V_{SS}–0.3		0.2 V_{CC}	V		
V_{OH1}	Output High Voltage	2.0-5.5	V_{CC}–0.4			V	I_{OH} = –0.5mA	

Table 11. GP323HA DC Characteristics (Continued)

			T_A= -40°C to +125°C					
Symbol	**Parameter**	**V_{CC}**	**Min**	**Typ(7)**	**Max**	**Units**	**Conditions**	**Notes**
V_{HVD}	Vcc High Voltage Detection			2.7		V		

Notes:

1. All outputs unloaded, inputs at rail.
2. CL1 = CL2 = 100 pF.
3. Oscillator stopped.
4. Oscillator stops when V_{CC} falls below V_{BO} limit.
5. It is strongly recommended to add a filter capacitor (minimum 0.1 µF), physically close to VCC and V_{SS} pins if operating voltage fluctuations are anticipated, such as those resulting from driving an Infrared LED.
6. Comparator and Timers are on. Interrupt disabled.
7. Typical values shown are at 25 degrees C.

Table 12. EPROM/OTP Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Notes
	Erase Time	15			Minutes	1,3
	Data Retention @ use years		10		Years	2
	Program/Erase Endurance	100			Cycles	1

Notes:
1. For windowed cerdip package only.
2. Standard: 0°C to 70°C; Extended: -40°C to +105°C; Automotive: -40°C to +125°C. Determined using the Arrhenius model, which is an industry standard for estimating data retention of floating gate technologies:

AF = exp[(Ea/k)*(1/Tuse - 1/TStress)]
Where:
Ea is the intrinsic activation energy (eV; typ. 0.8)
k is Boltzman’s constant (8.67 x 10-5 eV/°K)
°K = -273.16°C
Tuse = Use Temperature in °K
TStress = Stress Temperature in °K

3. At a stable UV Lamp output of $20mW/CM^2$

AC Characteristics

Figure 8 and Table 13 describe the Alternating Current (AC) characteristics.

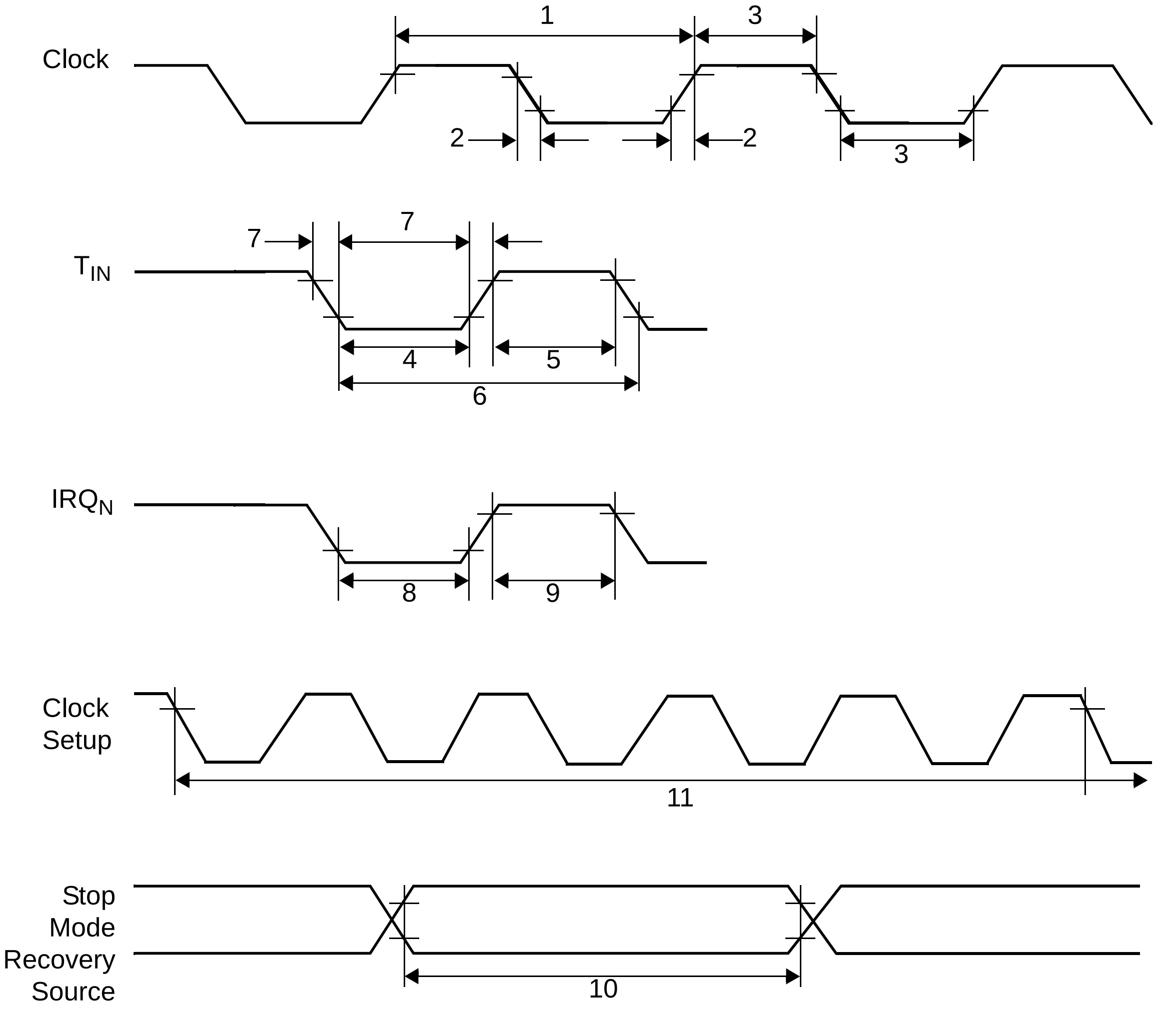


Figure 8. AC Timing Diagram

Pin Functions

XTAL1 Crystal 1 (Time-Based Input)

This pin connects a parallel-resonant crystal or ceramic resonator to the on-chip oscillator input. Additionally, an optional external single-phase clock can be coded to the on-chip oscillator input.

XTAL2 Crystal 2 (Time-Based Output)

This pin connects a parallel-resonant crystal or ceramic resonant to the on-chip oscillator output.

Port 0 (P07–P00)

Port 0 is an 8-bit, bidirectional, CMOS-compatible port. These eight I/O lines are configured under software control as a nibble I/O port. The output drivers are push-pull or open-drain controlled by bit D2 in the PCON register.

If one or both nibbles are needed for I/O operation, they must be configured by writing to the Port 0 mode register. After a hardware reset, Port 0 is configured as an input port.

An optional pull-up transistor is available as a mask option on all Port 0 bits with nibble select.

Notes: Internal pull-ups are disabled on any given pin or group of port pins when programmed into output mode.

The Port 0 direction is reset to its default state following an SMR.

The counter/timers are mapped into ERF group D. Access is easily performed using the following:

```
LD                      RP, #0Dh                ; Select ERF D
for access to bank D
                                                ; (working
register group 0)
LD                      R0,#xx                  ; load CTR0
LD                      1, #xx                  ; load CTR1
LD                      R1, 2                   ; CTR2→CTR1

LD                      RP, #0Dh                ; Select ERF D
for access to bank D
                                                ; (working
register group 0)
LD                      RP, #7Dh                ; Select
expanded register bank D and working            ; register
group 7 of bank 0 for access.
LD                      71h, 2
; CTRL2→register 71h
LD                      R1, 2
; CTRL2→register 71h
```

Register File

The register file (bank 0) consists of 4 I/O port registers, 237 general-purpose registers, 16 control and status registers (R0–R3, R4–R239, and R240–R255, respectively), and two expanded registers groups in Banks D (see Table 15) and F. Instructions can access registers directly or indirectly through an 8-bit address field, thereby allowing a short, 4-bit register address to use the Register Pointer (Figure 17). In the 4-bit mode, the register file is divided into 16 working register groups, each occupying 16 continuous locations. The Register Pointer addresses the starting location of the active working register group.

Note: Working register group E0–EF can only be accessed through working registers and indirect addressing modes.

into LO8; if it is a negative edge, data is put into HI8. From that point, one of the edge detect status bits (CTR1, D1; D0) is set, and an interrupt can be generated if enabled (CTR0, D2). Meanwhile, T8 is loaded with `FFh` and starts counting again. If T8 reaches 0, the timeout status bit (CTR0, D5) is set, and an interrupt can be generated if enabled (CTR0, D1). T8 then continues counting from `FFH` (see Figure 23 and Figure 24).

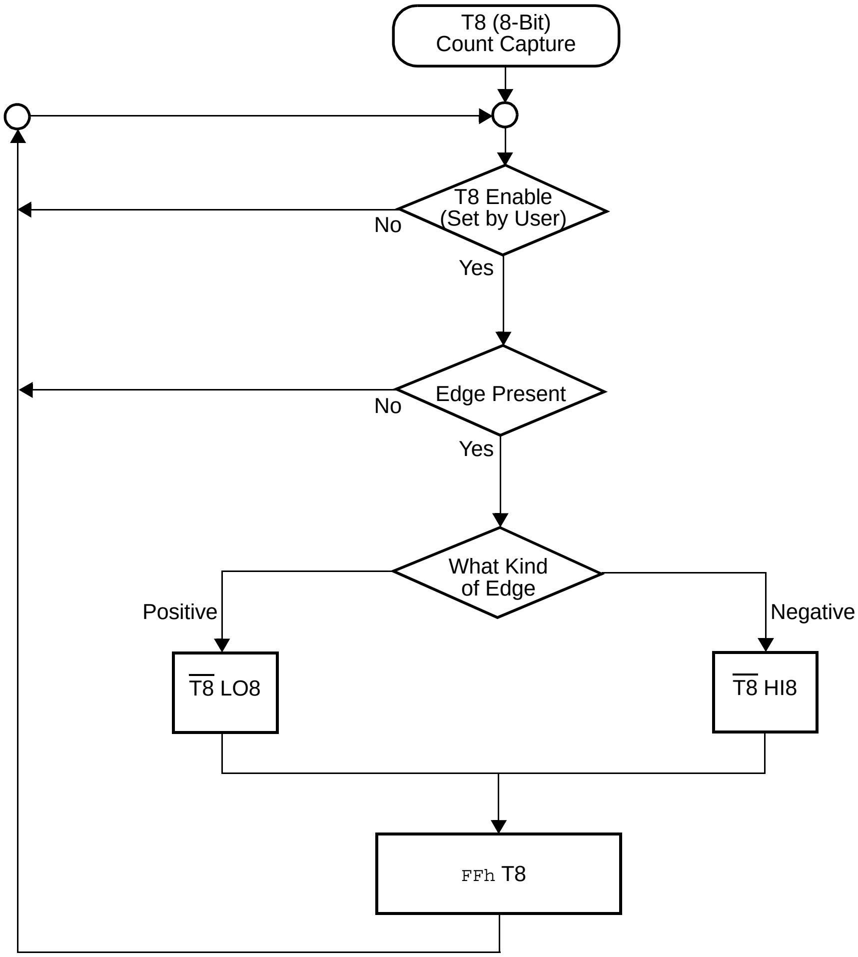


Figure 23. Demodulation Mode Count Capture Flowchart

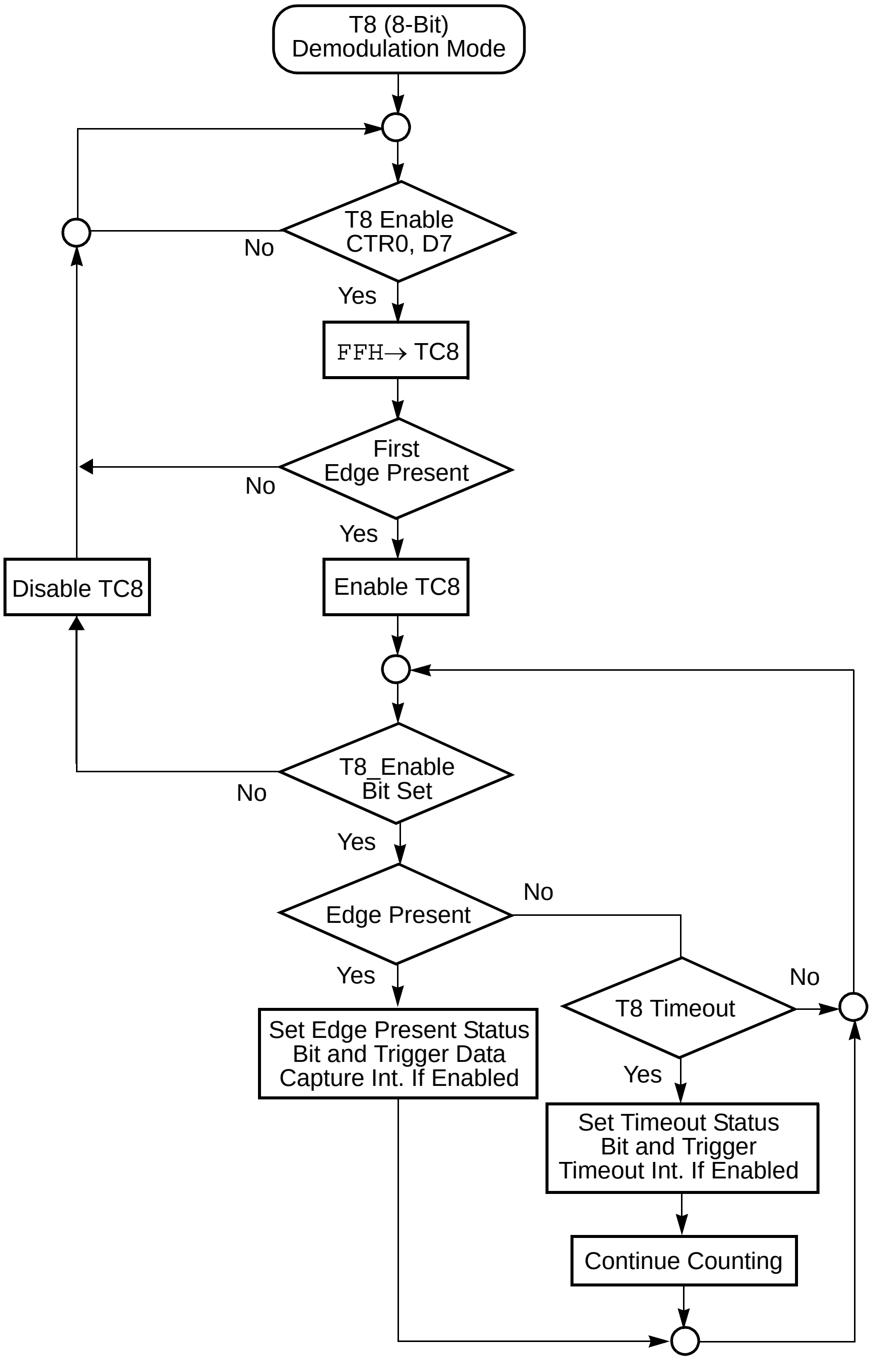


Figure 24. Demodulation Mode Flowchart

Caution: Do not load these registers at the time the values are to be loaded into the counter/timer to ensure known operation. An initial count of 1 is not allowed. An initial count of 0 causes T16 to count from 0 to `FFFFH` to `FFFEH`. Transition from 0 to `FFFFH` is not a timeout condition.

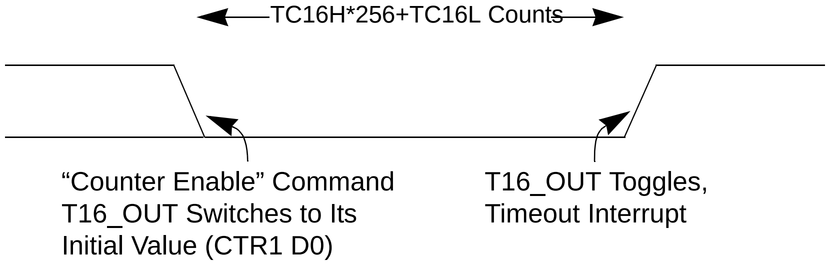


Figure 26. T16_OUT in Single-Pass Mode

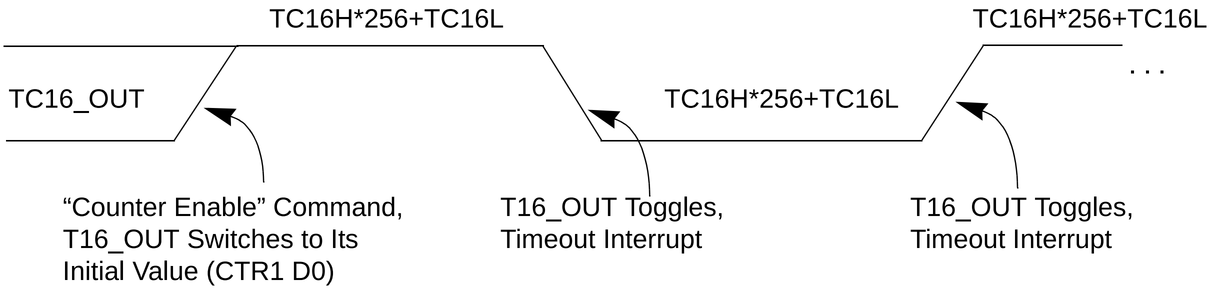


Figure 27. T16_OUT in Modulo-N Mode

T16 DEMODULATION Mode

The user must program TC16L and TC16H to `FFH`. After T16 is enabled, and the first edge (rising, falling, or both depending on CTR1 D5; D4) is detected, T16 captures HI16 and LO16, reloads, and begins counting.

If D6 of CTR2 Is 0

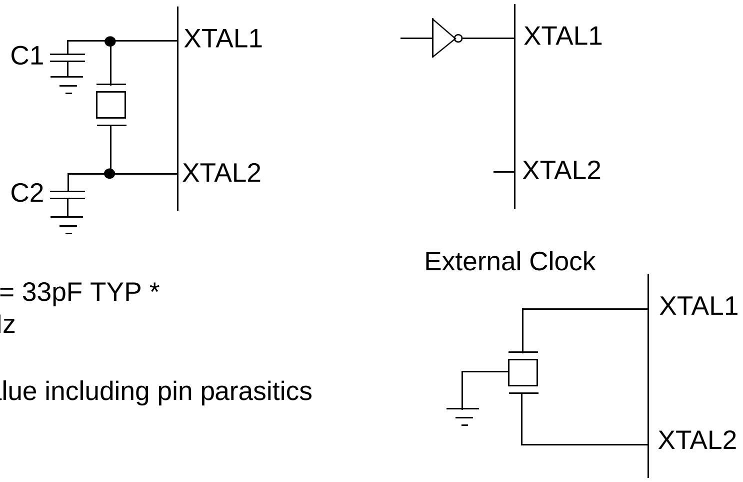
When a subsequent edge (rising, falling, or both depending on CTR1, D5; D4) is detected during counting, the current count in T16 is complemented and put into HI16 and LO16. When data is captured, one of the edge detect status bits (CTR1, D1; D0) is set, and an interrupt is generated if enabled (CTR2, D2). T16 is loaded with `FFFFH` and starts again.

This T16 mode is generally used to measure space time, the length of time between bursts of carrier signal (marks).

Clock

The device’s on-chip oscillator has a high-gain, parallel-resonant amplifier, for connection to a crystal or ceramic resonator, or any suitable external clock source (XTAL1 = Input, XTAL2 = Output). The crystal must be AT cut, 1 MHz to 8 MHz maximum, with a series resistance (RS) less than or equal to 100 Ω. The on-chip oscillator can be driven with a suitable external clock source.

The crystal must be connected across XTAL1 and XTAL2 using the recommended capacitors (capacitance greater than or equal to 22 pF) from each pin to ground.



Crystal
C1, C2 = 33pF TYP *
f = 8MHz

* Preliminary value including pin parasitics

External Clock

Ceramic Resonator
f = 8mHz

Figure 31. Oscillator Configuration

```
   FF          NOP          ; clear the pipeline
   6F          Stop         ; enter Stop Mode
```

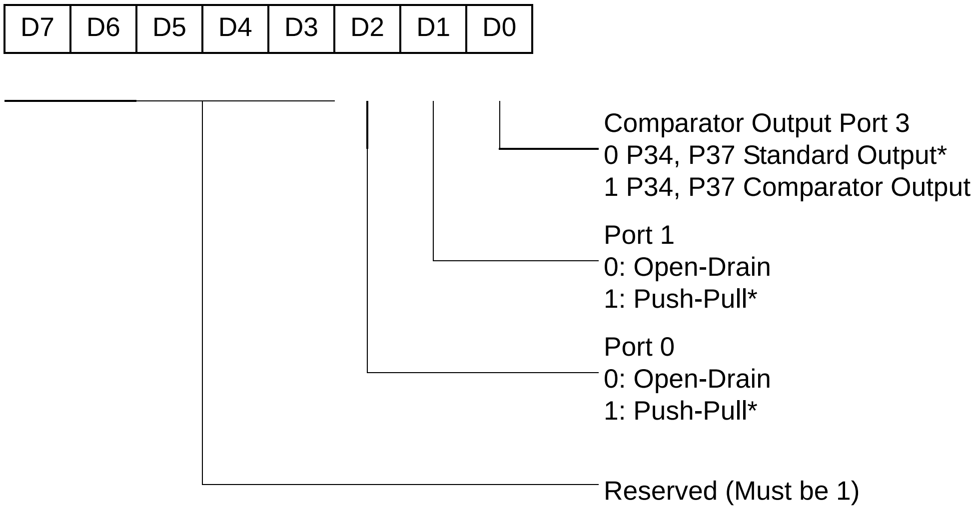
or

```
   FF          NOP          ; clear the pipeline
   7F          HALT         ; enter HALT Mode
```

Port Configuration Register

The Port Configuration (PCON) register (Figure 32) configures the comparator output on Port 3. It is located in the expanded register 2 at Bank F, location 00.

PCON(FH)00H



* Default setting after reset

Figure 32. Port Configuration Register (PCON) (Write Only)

Comparator Output Port 3 (D0)

Bit 0 controls the comparator used in Port 3. A 1 in this location brings the comparator outputs to P34 and P37, and a 0 releases the Port to its standard I/O configuration.

Port 1 Output Mode (D1)

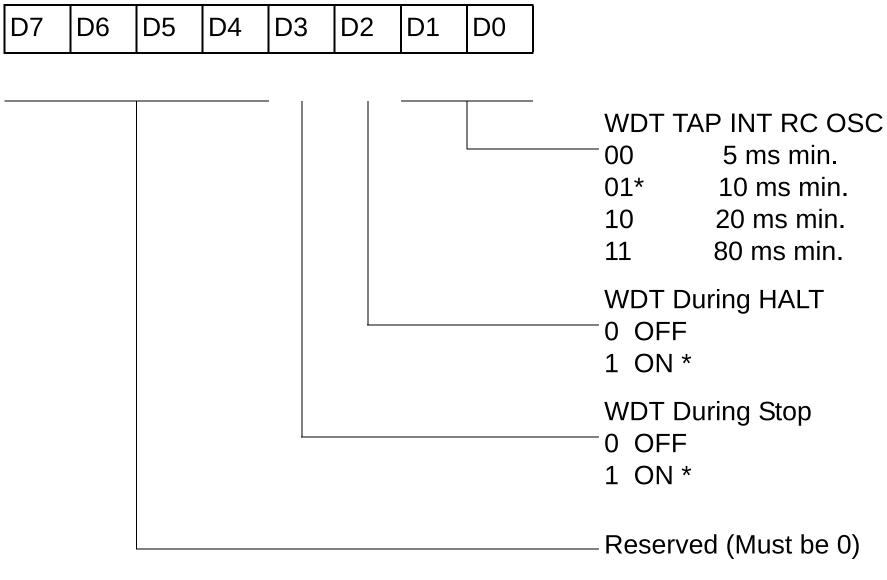
Bit 1 controls the output mode of port 1. A 1 in this location sets the output to push-pull, and a 0 sets the output to open-drain.

Watch-Dog Timer Mode Register (WDTMR)

The Watch-Dog Timer (WDT) is a retriggerable one-shot timer that resets the Z8® CPU if it reaches its terminal count. The WDT must initially be enabled by executing the WDT instruction. On subsequent executions of the WDT instruction, the WDT is refreshed. The WDT circuit is driven by an on-board RC-oscillator. The WDT instruction affects the Zero (Z), Sign (S), and Overflow (V) flags.

The POR clock source the internal RC-oscillator. Bits 0 and 1 of the WDT register control a tap circuit that determines the minimum timeout period. Bit 2 determines whether the WDT is active during HALT, and Bit 3 determines WDT activity during Stop. Bits 4 through 7 are reserved (Figure 37). This register is accessible only during the first 60 processor cycles (120 XTAL clocks) from the execution of the first instruction after Power-On-Reset, Watch-Dog Reset, or a Stop-Mode Recovery (Figure 36). After this point, the register cannot be modified by any means (intentional or otherwise). The WDTMR cannot be read. The register is located in Bank F of the Expanded Register Group at address location `0Fh`. It is organized as shown in Figure 37.

WDTMR(0F)0Fh



* Default setting after reset

Figure 37. Watch-Dog Timer Mode Register (Write Only)

WDT Time Select (D0, D1)

This bit selects the WDT time period. It is configured as indicated in Table 23.

WDTMR During STOP (D3)

This bit determines whether or not the WDT is active during STOP Mode. Because the XTAL clock is stopped during STOP Mode, the on-board RC has to be selected as the clock source to the WDT/POR counter. A 1 indicates active during Stop. The default is 1.

EPROM Selectable Options

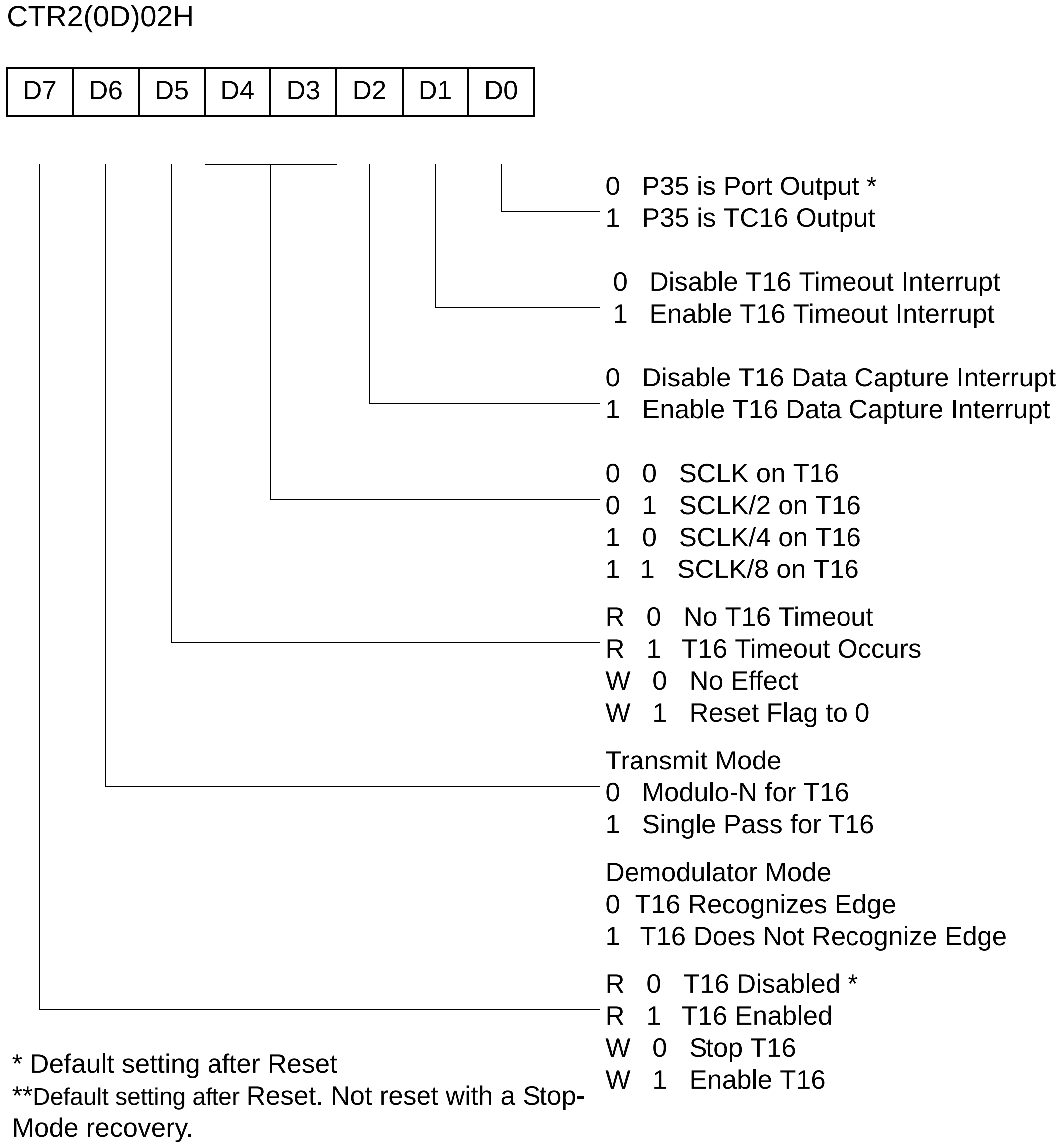
There are seven EPROM Selectable Options to choose from based on ROM code requirements. These options are listed in Table 24.

Table 24. EPROM Selectable Options

Port 00–03 Pull-Ups	On/Off
Port 04–07 Pull-Ups	On/Off
Port 10–13 Pull-Ups	On/Off
Port 14–17 Pull-Ups	On/Off
Port 20–27 Pull-Ups	On/Off
EPROM Protection	On/Off
Watch-Dog Timer at Power-On Reset	On/Off

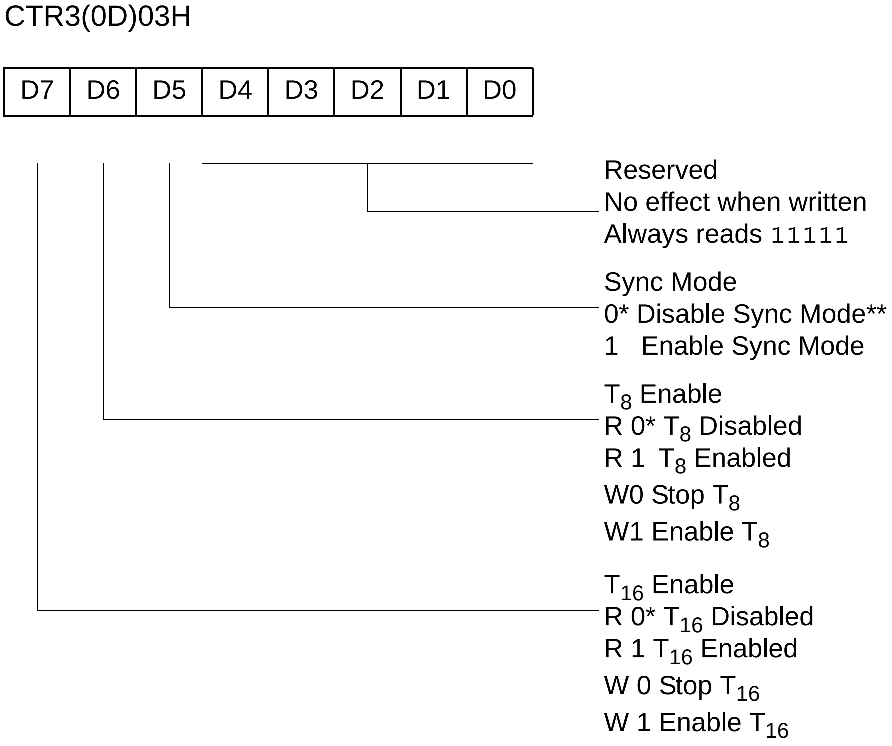
Voltage Brown-Out/Standby

An on-chip Voltage Comparator checks that the V_{DD} is at the required level for correct operation of the device. Reset is globally driven when V_{DD} falls below V_{BO}. A small drop in V_{DD} causes the XTAL1 and XTAL2 circuitry to stop the crystal or resonator clock. If the V_{DD} is allowed to stay above V_{RAM}, the RAM content is preserved. When the power level is returned to above V_{BO}, the device performs a POR and functions normally.



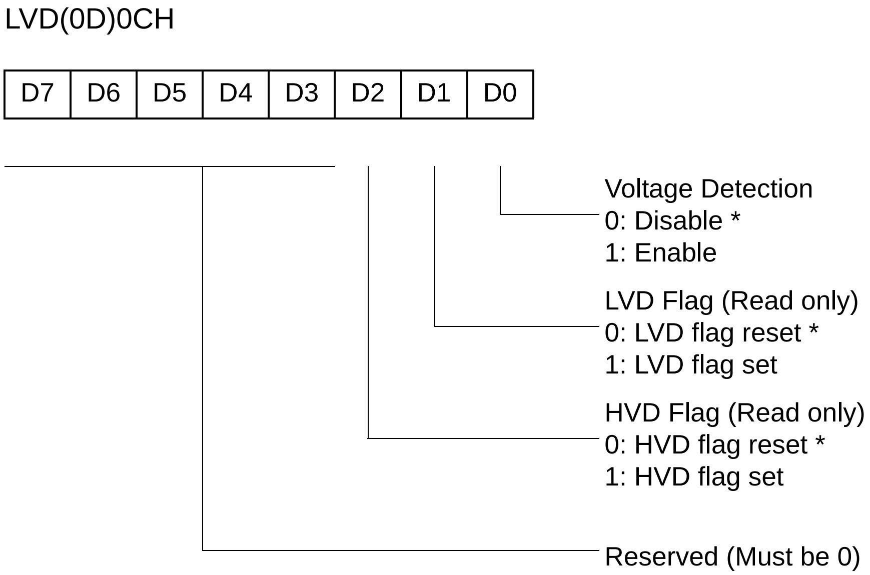
* Default setting after Reset
**Default setting after Reset. Not reset with a Stop-Mode recovery.

Figure 41. T16 Control Register ((0D) 2H: Read/Write Except Where Noted)



* Default setting after reset.
** Default setting after reset. Not reset with a Stop Mode recovery.

Figure 42. T8/T16 Control Register (0D)03H: Read/Write (Except Where Noted)



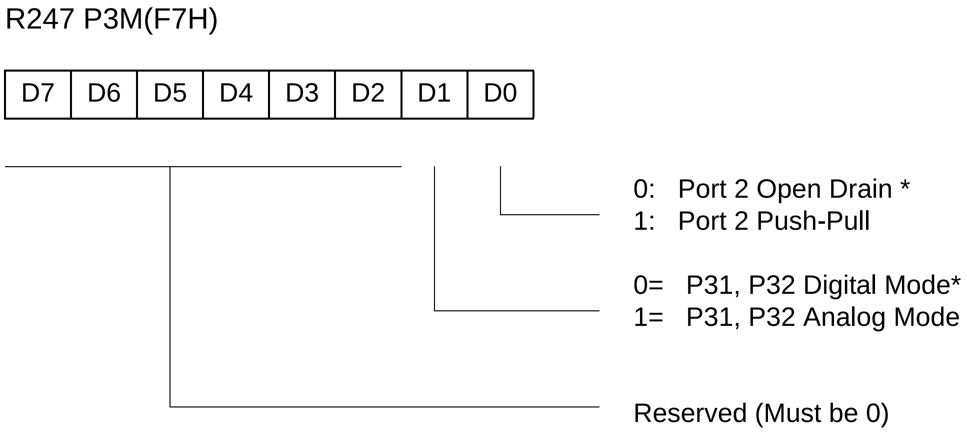
* Default setting after reset.

Figure 43. Voltage Detection Register

Note: Do not modify register P01M while checking a low-voltage condition. Switching noise of both ports 0 and 1 together might trigger the LVD flag.

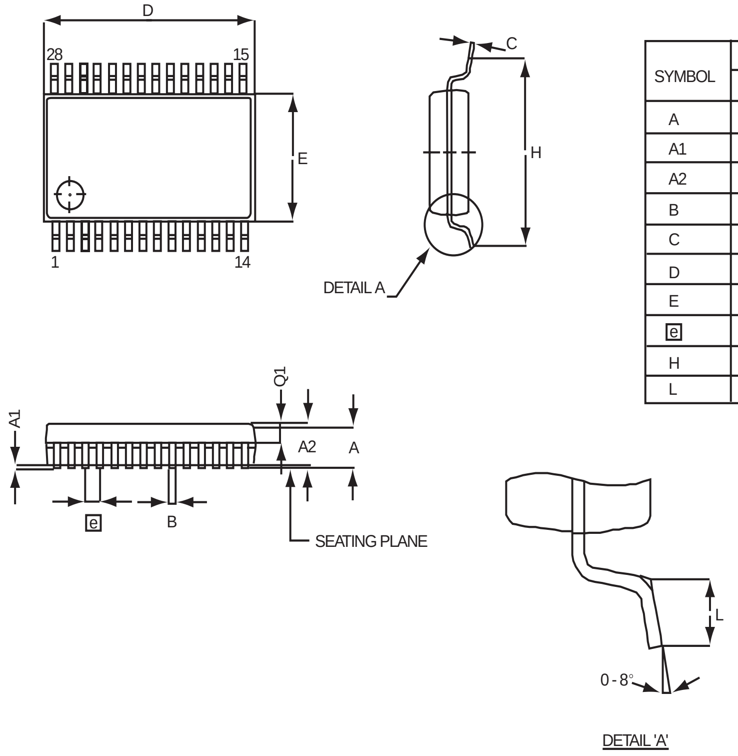
Expanded Register File Control Registers (0F)

The expanded register file control registers (0F) are depicted in Figures 44 through Figure 57.



* Default setting after reset. Not reset with a Stop Mode recovery.

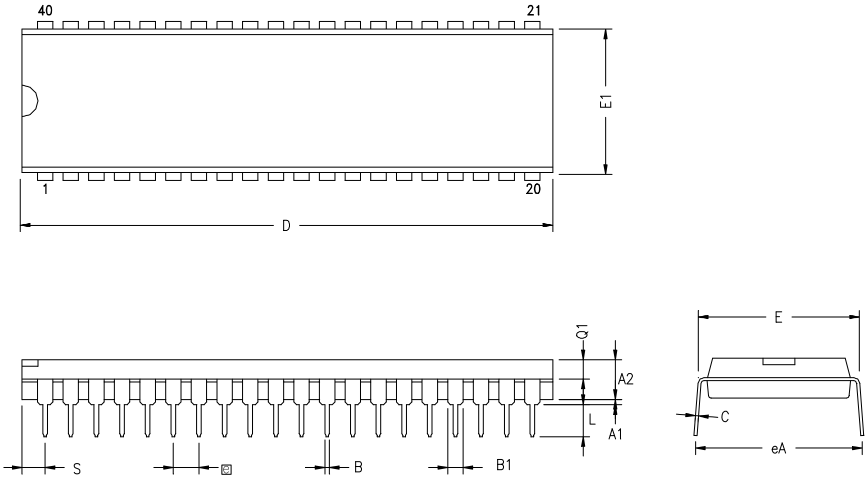
Figure 49. Port 3 Mode Register (F7H: Write Only)



SYMBOL	MILLIMETER			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.73	1.86	1.99	0.068	0.073	0.078
A1	0.05	0.13	0.21	0.002	0.005	0.008
A2	1.68	1.73	1.78	0.066	0.068	0.070
B	0.25		0.38	0.010		0.015
C	0.09	–	0.20	0.004	0.006	0.008
D	10.07	10.20	10.33	0.397	0.402	0.407
E	5.20	5.30	5.38	0.205	0.209	0.212
e	0.65 TYP			0.0256 TYP		
H	7.65	7.80	7.90	0.301	0.307	0.311
L	0.63	0.75	0.95	0.025	0.030	0.037

CONTROLLING DIMENSIONS: MM
LEADS ARE COPLANAR WITHIN .004 INCHES.

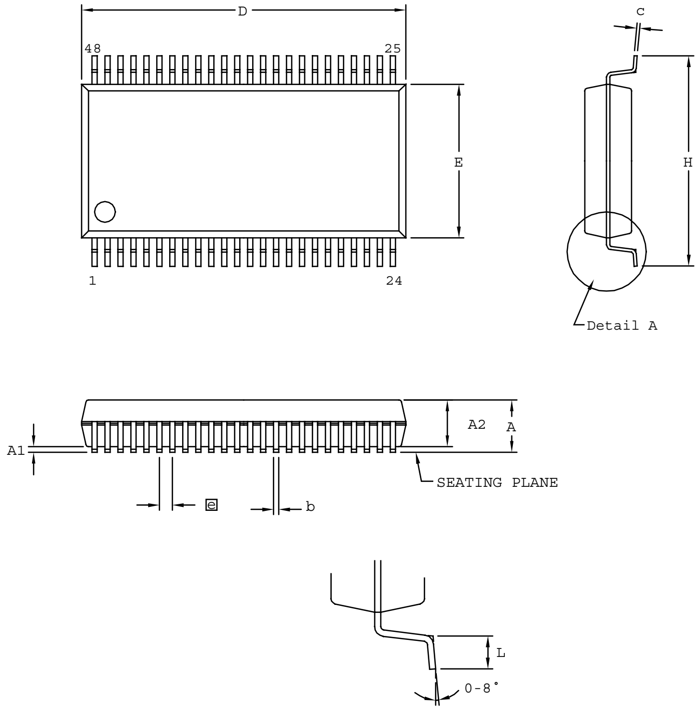
Figure 65. 28-Pin SSOP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.51	1.02	.020	.040
A2	3.18	3.94	.125	.155
B	0.38	0.53	.015	.021
B1	1.02	1.52	.040	.060
C	0.23	0.38	.009	.015
D	52.07	52.58	2.050	2.070
E	15.24	15.75	.600	.620
E1	13.59	14.22	.535	.560
e	2.54 TYP		.100 TYP	
eA	15.49	16.76	.610	.660
L	3.05	3.81	.120	.150
Q1	1.40	1.91	.055	.075
S	1.52	2.29	.060	.090

CONTROLLING DIMENSIONS : INCH

Figure 66. 40-Pin PDIP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	2.41	2.79	0.095	0.110
A1	0.23	0.38	0.009	0.015
A2	2.18	2.39	0.086	0.094
b	0.20	0.34	0.008	0.0135
c	0.13	0.25	0.005	0.010
D	15.75	16.00	0.620	0.630
E	7.39	7.59	0.291	0.299
e	0.635 BSC		0.025 BSC	
H	10.16	10.41	0.400	0.410
L	0.51	1.016	0.020	0.040

CONTROLLING DIMENSIONS : MM
LEADS ARE COPLANAR WITHIN .004 INCH

Figure 68. 48-Pin SSOP Package Design

Note: Check with ZiLOG on the actual bonding diagram and coordinate for chip-on-board assembly.

16KB Standard Temperature: 0° to +70°C

Part Number	Description	Part Number	Description
ZGP323HSH4816C	48-pin SSOP 16K OTP	ZGP323HSS2816C	28-pin SOIC 16K OTP
ZGP323HSP4016C	40-pin PDIP 16K OTP	ZGP323HSH2016C	20-pin SSOP 16K OTP
ZGP323HSH2816C	28-pin SSOP 16K OTP	ZGP323HSP2016C	20-pin PDIP 16K OTP
ZGP323HSP2816C	28-pin PDIP 16K OTP	ZGP323HSS2016C	20-pin SOIC 16K OTP

16KB Extended Temperature: -40° to +105°C

Part Number	Description	Part Number	Description
ZGP323HEH4816C	48-pin SSOP 16K OTP	ZGP323HES2816C	28-pin SOIC 16K OTP
ZGP323HEP4016C	40-pin PDIP 16K OTP	ZGP323HEH2016C	20-pin SSOP 16K OTP
ZGP323HEH2816C	28-pin SSOP 16K OTP	ZGP323HEP2016C	20-pin PDIP 16K OTP
ZGP323HEP2816C	28-pin PDIP 16K OTP	ZGP323HES2016C	20-pin SOIC 16K OTP

16KB Automotive Temperature: -40° to +125°C

Part Number	Description	Part Number	Description
ZGP323HAH4816C	48-pin SSOP 16K OTP	ZGP323HAS2816C	28-pin SOIC 16K OTP
ZGP323HAP4016C	40-pin PDIP 16K OTP	ZGP323HAH2016C	20-pin SSOP 16K OTP
ZGP323HAH2816C	28-pin SSOP 16K OTP	ZGP323HAP2016C	20-pin PDIP 16K OTP
ZGP323HAP2816C	28-pin PDIP 16K OTP	ZGP323HAS2016C	20-pin SOIC 16K OTP
Replace C with G for Lead-Free Packaging			